

12-OUTPUT LOW POWER DIFFERENTIAL BUFFER FOR PCIE GEN1/2/3 AND QPI 9ZXL1231

General Description

The 9ZXL1231 is a low power 12-output differential buffer that meets all the performance requirements of the Intel DB1900Z specification. It is pin compatible to the 9ZX21201. The 9ZXL1231 is backwards compatible to PCIe Gen2 and QPI 6.4GT/s specifications. A fixed, internal feedback path maintains low drift for critical QPI applications.

Recommended Application

12-Output Low Power Differential Buffer for PCIe Gen1/2/3 & QPI

Output Features

- 12 - 0.7V low-power HCSL-compatible output pairs

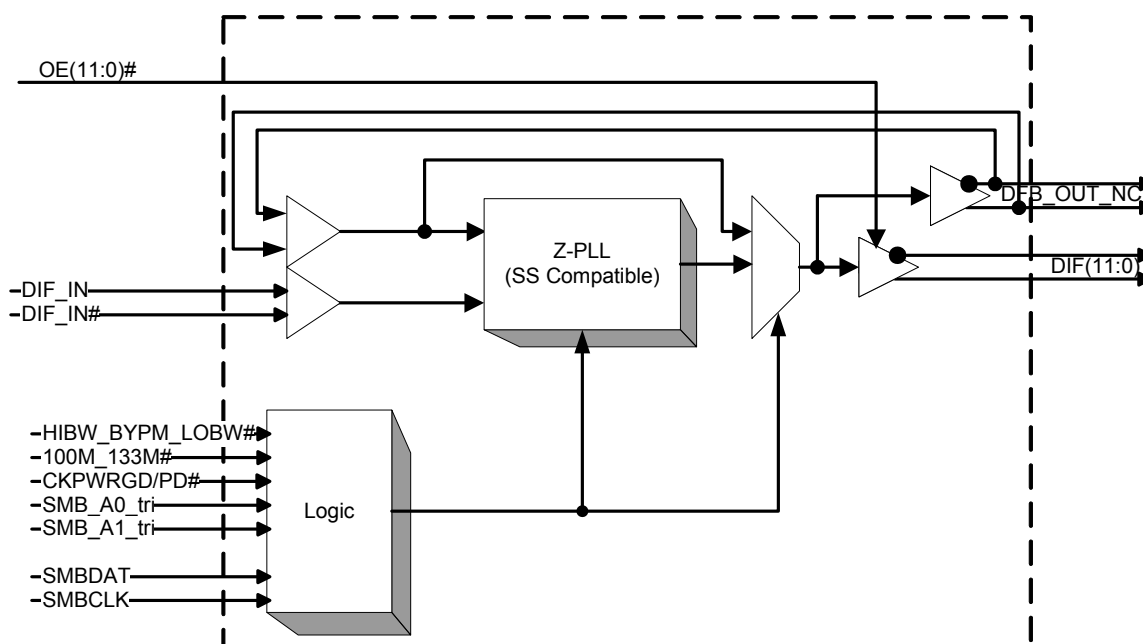
Features/Benefits

- Low-power push-pull outputs; Save power and board space - no Rp
- Pin compatible to 9ZX21201; easy path to >50% power savings
- Space-saving 64-pin QFN package
- Fixed feedback path for Ops input-to-output delay
- 9 Selectable SMBus Addresses; Multiple devices can share the same SMBus Segment
- 12 OE# pins; Hardware control of each output
- PLL or bypass mode; PLL can dejitter incoming clock
- 100MHz or 133MHz PLL mode operation; supports PCIe and QPI applications
- Selectable PLL bandwidth; minimizes jitter peaking in downstream PLL's
- Spread Spectrum Compatible; tracks spreading input clock for low EMI

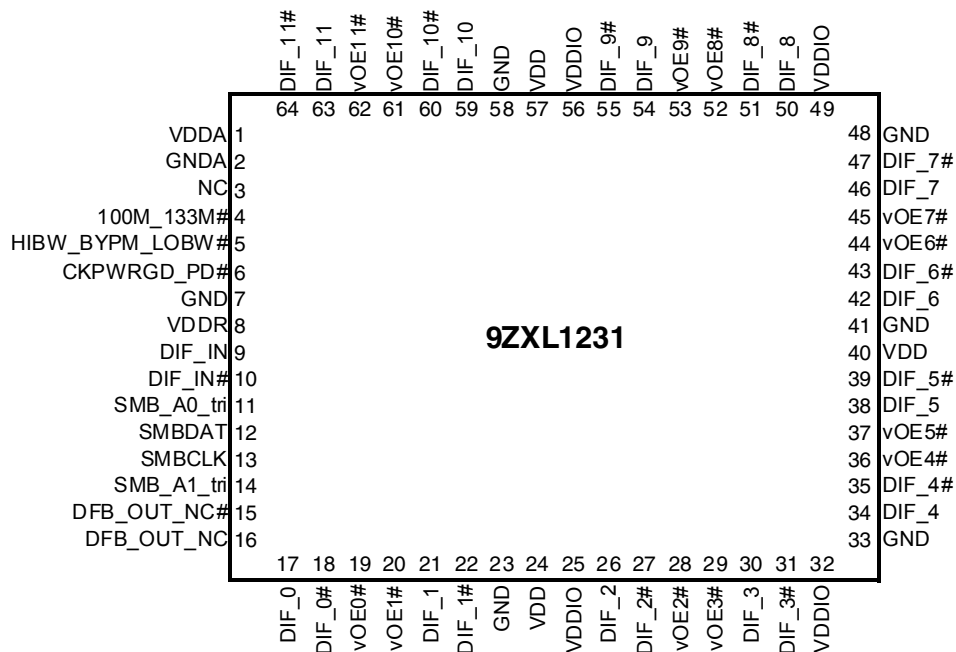
Key Specifications

- Cycle-to-cycle jitter <50ps
- Output-to-output skew <65 ps
- Input-to-output delay variation <50ps
- PCIe Gen3 phase jitter <1.0ps RMS
- QPI 9.6GT/s 12UI phase jitter <0.2ps RMS

Block Diagram



Pin Configuration



Note: Pins with ^ prefix have internal 120K pullup
Pins with v prefix have internal 120K pulldown

Power Management Table

CKPWRGD_PD#	DIF_IN/ DIF_IN#	SMBus EN bit	DIF(11:0)/ DIF(1:0)#	PLL STATE IF NOT IN BYPASS MODE
0	X	X	Low/Low	OFF
1	Running	0	Low/Low	ON
		1	Running	ON

Functionality at Power-up (PLL mode)

100M_133M#	DIF_IN MHz	DIF(11:0)
1	100.00	DIF_IN
0	133.33	DIF_IN

Power Connections

Pin Number			Description
VDD	VDDIO	GND	
1		2	Analog PLL
8		7	Analog Input
24,40,57	25,32,49,56	23,33,41,48,58	DIF clocks

PLL Operating Mode Readback Table

HiBW_BypM_LoBW#	Byte0, bit 7	Byte 0, bit 6
Low (Low BW)	0	0
Mid (Bypass)	0	1
High (High BW)	1	1

Tri-Level Input Thresholds

Level	Voltage
Low	<0.8V
Mid	1.2<Vin<1.8V
High	Vin > 2.2V

PLL Operating Mode

HiBW_BypM_LoBW#	MODE
Low	PLL Lo BW
Mid	Bypass
High	PLL Hi BW

NOTE: PLL is OFF in Bypass Mode

9ZXL1231 SMBus Addressing

Pin		
SMB_A1_tri	SMB_A0_tri	SMBus Address
0	0	D8
0	M	DA
0	1	DE
M	0	C2
M	M	C4
M	1	C6
1	0	CA
1	M	CC
1	1	CE

Pin Descriptions

PIN #	PIN NAME	TYPE	DESCRIPTION
1	VDDA	PWR	3.3V power for the PLL core.
2	GNDA	PWR	Ground pin for the PLL core.
3	NC	N/A	No Connection.
4	100M_133M#	IN	3.3V Input to select operating frequency. See Functionality Table for Definition
5	HIBW_BYPM_LOBW#	IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
6	CKPWRGD_PD#	IN	3.3V Input notifies device to sample latched inputs and start up on first high assertion, or exit Power Down Mode on subsequent assertions. Low enters Power Down Mode.
7	GND	PWR	Ground pin.
8	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
9	DIF_IN	IN	0.7 V Differential TRUE input
10	DIF_IN#	IN	0.7 V Differential Complementary Input
11	SMB_A0_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A1 to decode 1 of 9 SMBus Addresses.
12	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
13	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
14	SMB_A1_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SMB_A0 to decode 1 of 9 SMBus Addresses.
15	DFB_OUT_NC#	OUT	Complementary half of differential feedback output, provides feedback signal to the PLL for synchronization with input clock to eliminate phase error. This pin should NOT be connected on the circuit board, the feedback is internal to the package.
16	DFB_OUT_NC	OUT	True half of differential feedback output, provides feedback signal to the PLL for synchronization with the input clock to eliminate phase error. This pin should NOT be connected on the circuit board, the feedback is internal to the package.
17	DIF_0	OUT	0.7V differential true clock output
18	DIF_0#	OUT	0.7V differential Complementary clock output
19	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down resistor. 1 =disable outputs, 0 = enable outputs
20	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
21	DIF_1	OUT	0.7V differential true clock output
22	DIF_1#	OUT	0.7V differential Complementary clock output
23	GND	PWR	Ground pin.
24	VDD	PWR	Power supply, nominal 3.3V
25	VDDIO	PWR	Power supply for differential outputs
26	DIF_2	OUT	0.7V differential true clock output
27	DIF_2#	OUT	0.7V differential Complementary clock output
28	vOE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
29	vOE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
30	DIF_3	OUT	0.7V differential true clock output
31	DIF_3#	OUT	0.7V differential Complementary clock output
32	VDDIO	PWR	Power supply for differential outputs
33	GND	PWR	Ground pin.
34	DIF_4	OUT	0.7V differential true clock output
35	DIF_4#	OUT	0.7V differential Complementary clock output
36	vOE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
37	vOE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs

Pin Descriptions (cont.)

38	DIF_5	OUT	0.7V differential true clock output
39	DIF_5#	OUT	0.7V differential Complementary clock output
40	VDD	PWR	Power supply, nominal 3.3V
41	GND	PWR	Ground pin.
42	DIF_6	OUT	0.7V differential true clock output
43	DIF_6#	OUT	0.7V differential Complementary clock output
44	vOE6#	IN	Active low input for enabling DIF pair 6. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
45	vOE7#	IN	Active low input for enabling DIF pair 7. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
46	DIF_7	OUT	0.7V differential true clock output
47	DIF_7#	OUT	0.7V differential Complementary clock output
48	GND	PWR	Ground pin.
49	VDDIO	PWR	Power supply for differential outputs
50	DIF_8	OUT	0.7V differential true clock output
51	DIF_8#	OUT	0.7V differential Complementary clock output
52	vOE8#	IN	Active low input for enabling DIF pair 8. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
53	vOE9#	IN	Active low input for enabling DIF pair 9. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
54	DIF_9	OUT	0.7V differential true clock output
55	DIF_9#	OUT	0.7V differential Complementary clock output
56	VDDIO	PWR	Power supply for differential outputs
57	VDD	PWR	Power supply, nominal 3.3V
58	GND	PWR	Ground pin.
59	DIF_10	OUT	0.7V differential true clock output
60	DIF_10#	OUT	0.7V differential Complementary clock output
61	vOE10#	IN	Active low input for enabling DIF pair 10. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
62	vOE11#	IN	Active low input for enabling DIF pair 11. This pin has an internal pull-down 1 =disable outputs, 0 = enable outputs
63	DIF_11	OUT	0.7V differential true clock output
64	DIF_11#	OUT	0.7V differential Complementary clock output

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9ZXL1231. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDD, VDDA, VDDR	VDD for core logic and PLL			4.6	V	1,2
IO Supply Voltage	VDD_IO	VDD for differential IO			4.6	V	1,2
Input Low Voltage	V _{IL}		GND-0.5			V	1
Input High Voltage	V _{IH}	Except for SMBus interface			V _{DD} +0.5V	V	1
Input High Voltage	V _{IHSMB}	SMBus clock and data pins			5.5V	V	1
Storage Temperature	T _s		-65		150	°C	1
Junction Temperature	T _j				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

²Operation under these conditions is neither implied nor guaranteed.

Electrical Characteristics—Clock Input Parameters

T_A = T_{COM}; Supply Voltage V_{DD} = 3.3 V +/-5%, VDD_IO = 1.05 to 3.3V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V _{IHDIF}	Differential inputs (single-ended measurement)	600	800	1150	mV	1
Input Low Voltage - DIF_IN	V _{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1
Input Common Mode Voltage - DIF_IN	V _{COM}	Common Mode Input Voltage	300		1000	mV	1
Input Amplitude - DIF_IN	V _{SWING}	Peak to Peak value (single-ended measurement)	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	V _{IN} = V _{DD} , V _{IN} = GND	-5		5	uA	1
Input Duty Cycle	d _{tin}	Measurement from differential waveform	45		55	%	1
Input Jitter - Cycle to Cycle	J _{DIFin}	Differential Measurement	0		125	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics–Input/Supply/Common Output Parameters

$T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3\text{ V} \pm 5\%$, $V_{DD_IO} = 1.05\text{ to }3.3\text{ V} \pm 5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Ambient Operating Temperature	T_{COM}	Commercial range	0		70	°C
Input High Voltage	V_{IH}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		$V_{DD} + 0.3$	V
Input Low Voltage	V_{IL}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	$GND - 0.3$		0.8	V
Input Current	I_{IN}	Single-ended inputs, $V_{IN} = GND$, $V_{IN} = V_{DD}$	-5		5	µA
	I_{INP}	Single-ended inputs $V_{IN} = 0\text{ V}$; Inputs with internal pull-up resistors $V_{IN} = V_{DD}$; Inputs with internal pull-down resistors	-200		200	µA
Input Frequency	F_{ibyp}	$V_{DD} = 3.3\text{ V}$, Bypass mode	33		150	MHz
	F_{ipll}	$V_{DD} = 3.3\text{ V}$, 100MHz PLL mode	90	100.00	110	MHz
	F_{ipll}	$V_{DD} = 3.3\text{ V}$, 133.33MHz PLL mode	120	133.33	147	MHz
Pin Inductance	L_{pin}				7	nH
Capacitance	C_{IN}	Logic Inputs, except DIF_IN	1.5		5	pF
	C_{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF
	C_{OUT}	Output pin capacitance			6	pF
Clk Stabilization	T_{STAB}	From V_{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.250	1	ms
Input SS Modulation Frequency	f_{MODIN}	Allowable Frequency (Triangular Modulation)	30		33	kHz
OE# Latency	$t_{LATO\#}$	DIF start after OE# assertion DIF stop after OE# deassertion	4		12	cycles
Tdrive_PD#	$t_{DRV\#}$	DIF output enable after PD# de-assertion			300	µs
Tfall	t_F	Fall time of control inputs			10	ns
Trise	t_R	Rise time of control inputs			10	ns
SMBus Input Low Voltage	V_{ILSMB}				0.8	V
SMBus Input High Voltage	V_{IHSMB}		2.1		V_{DDSMB}	V
SMBus Output Low Voltage	V_{OLSMB}	@ I_{PULLUP}			0.4	V
SMBus Sink Current	I_{PULLUP}	@ V_{OL}	4			mA
Nominal Bus Voltage	V_{DDSMB}	3V to 5V +/- 10%	2.7		5.5	V
SCLK/SDATA Rise Time	t_{RSMB}	(Max $V_{IL} - 0.15$) to (Min $V_{IH} + 0.15$)			1000	ns
SCLK/SDATA Fall Time	t_{FSMB}	(Min $V_{IH} + 0.15$) to (Max $V_{IL} - 0.15$)			300	ns
SMBus Operating Frequency	f_{MAXSMB}	Maximum SMBus operating frequency			100	kHz

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

⁴DIF_IN input

⁵The differential input clock must be running for the SMBus to be active

Electrical Characteristics–DIF 0.7V Low Power Differential Outputs

$T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3\text{ V} \pm 5\%$, $V_{DD_IO} = 1.05\text{ to }3.3\text{ V} \pm 5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	T_{rf}	Scope averaging on	1	3.3	4	V/ns	1, 2, 3
Slew rate matching	ΔT_{rf}	Slew rate matching, Scope averaging on		7	20	%	1, 2, 4
Voltage High	V_{High}	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	660	778	850	mV	1
Voltage Low	V_{Low}		-150	0	150		1
Max Voltage	V_{max}	Measurement on single ended signal using absolute value. (Scope averaging off)		868	1150	mV	1
Min Voltage	V_{min}		-300	-64			1
Vswing	V_{swing}	Scope averaging off	300	1556		mV	1, 2
Crossing Voltage (abs)	V_{cross_abs}	Scope averaging off	300	430	550	mV	1, 5
Crossing Voltage (var)	ΔV_{cross}	Scope averaging off		17	140	mV	1, 6

¹Guaranteed by design and characterization, not 100% tested in production. $C_L = 2\text{ pF}$ with $R_S = 27\Omega$ for $Z_0 = 85\Omega$ differential trace impedance).

²Measured from differential waveform

³Slew rate is measured through the V_{swing} voltage range centered around differential 0V. This results in a $\pm 150\text{ mV}$ window around differential 0V.

⁴Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a $\pm 75\text{ mV}$ window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of $V_{cross_min/max}$ (V_{cross} absolute) allowed. The intent is to limit V_{cross} induced modulation by setting ΔV_{cross} to be smaller than V_{cross} absolute.

Electrical Characteristics–Current Consumption

$T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3\text{ V} \pm 5\%$, $V_{DD_IO} = 1.05\text{ to }3.3\text{ V} \pm 5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Current	I_{DDVDD}	133MHz, VDD rail		18	25	mA	1
	I_{DDVDDA}	133MHz, VDDA + VDDR rail, PLL Mode		16	20	mA	1
	$I_{DDVDDIO}$	133MHz, C_L = Full load; VDD IO rail		101	110	mA	1
Powerdown Current	$I_{DDVDDPD}$	Power Down, VDD Rail		0.01	1	mA	1
	$I_{DDVDDAPD}$	Power Down, VDDA Rail		3	5	mA	1
	$I_{DDVDDIOPD}$	Power Down, VDD_IO Rail		0.01	0.2	mA	1

¹Guaranteed by design and characterization, not 100% tested in production.

² $C_L = 2\text{ pF}$ with $R_S = 27\Omega$ for $Z_0 = 85\Omega$ differential trace impedance

Electrical Characteristics—Skew and Differential Jitter Parameters

$T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3\text{ V} \pm 5\%$, $V_{DD_IO} = 1.05\text{ to }3.3\text{ V} \pm 5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
CLK_IN, DIF[x:0]	t_{SPO_PLL}	Input-to-Output Skew in PLL mode nominal value @ 25°C, 3.3V	-100	-60	100	ps	1,2,4,5,8
CLK_IN, DIF[x:0]	t_{PD_BYP}	Input-to-Output Skew in Bypass mode nominal value @ 25°C, 3.3V	2.5	3.2	4.5	ns	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSPO_PLL}	Input-to-Output Skew Variation in PLL mode across voltage and temperature	-50	0	50	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSPO_BYP}	Input-to-Output Skew Variation in Bypass mode across voltage and temperature	-250		250	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DTE}	Random Differential Tracking error between two 9ZX devices in Hi BW Mode		3	5	ps (rms)	1,2,3,5,8
CLK_IN, DIF[x:0]	t_{DSSTE}	Random Differential Spread Spectrum Tracking error between two 9ZX devices in Hi BW Mode		10	75	ps	1,2,3,5,8
DIF{x:0}	t_{SKEW_ALL}	Output-to-Output Skew across all outputs (Common to Bypass and PLL mode)		21	65	ps	1,2,3,8
PLL Jitter Peaking	$j_{peak-hibw}$	LOBW#_BYPASS_HIBW = 1	0	1.2	2.5	dB	7,8
PLL Jitter Peaking	$j_{peak-lobw}$	LOBW#_BYPASS_HIBW = 0	0	0.8	2	dB	7,8
PLL Bandwidth	pll_{HIBW}	LOBW#_BYPASS_HIBW = 1	2	3	4	MHz	8,9
PLL Bandwidth	pll_{LOBW}	LOBW#_BYPASS_HIBW = 0	0.7	1.1	1.4	MHz	8,9
Duty Cycle	t_{DC}	Measured differentially, PLL Mode	45	50.1	55	%	1
Duty Cycle Distortion	t_{DCD}	Measured differentially, Bypass Mode @100MHz	-2	-0.6	2	%	1,10
Jitter, Cycle to cycle	$t_{jcy-cyc}$	PLL mode		34	50	ps	1,11
		Additive Jitter in Bypass Mode		5	50	ps	1,11

Notes for preceding table:

- ¹ $C_L = 2\text{ pF}$ with $R_S = 27\Omega$ for $Z_0 = 85\Omega$ differential trace impedance. Input to output skew is measured at the first output edge following the corresponding input.
- ² Measured from differential cross-point to differential cross-point. This parameter can be tuned with external feedback path, if present.
- ³ All Bypass Mode Input-to-Output specs refer to the timing between an input edge and the specific output edge created by it.
- ⁴ This parameter is deterministic for a given device
- ⁵ Measured with scope averaging on to find mean value.
- ⁶ t is the period of the input clock
- ⁷ Measured as maximum pass band gain. At frequencies within the loop BW, highest point of magnification is called PLL jitter peaking.
- ⁸ Guaranteed by design and characterization, not 100% tested in production.
- ⁹ Measured at 3 db down or half power point.
- ¹⁰ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.
- ¹¹ Measured from differential waveform

Electrical Characteristics–Phase Jitter Parameters

$T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3\text{ V} \pm 5\%$, $V_{DD_IO} = 1.05\text{ to }3.3\text{ V} \pm 5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Phase Jitter, PLL Mode	$t_{jphPCIEG1}$	PCIE Gen 1		34	86	ps (p-p)	1,2,3
	$t_{jphPCIEG2}$	PCIE Gen 2 Lo Band $10\text{kHz} < f < 1.5\text{MHz}$		1.2	3	ps (rms)	1,2
		PCIE Gen 2 High Band $1.5\text{MHz} < f < \text{Nyquist (50MHz)}$		2.2	3.1	ps (rms)	1,2
	$t_{jphPCIEG3}$	PCIE Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.5	1	ps (rms)	1,2,4
	t_{jphQPI_SMI}	QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.24	0.5	ps (rms)	1,5
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.14	0.3	ps (rms)	1,5
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.12	0.2	ps (rms)	1,5
AdditivePhase Jitter, Bypass mode	$t_{jphPCIEG1}$	PCIE Gen 1		3.7	10	ps (p-p)	1,2,3
	$t_{jphPCIEG2}$	PCIE Gen 2 Lo Band $10\text{kHz} < f < 1.5\text{MHz}$		0.1	0.3	ps (rms)	1,2,6
		PCIE Gen 2 High Band $1.5\text{MHz} < f < \text{Nyquist (50MHz)}$		0.4	0.6	ps (rms)	1,2,6
	$t_{jphPCIEG3}$	PCIE Gen 3 (PLL BW of 2-4MHz, 2-5MHz, CDR = 10MHz)		0.09	0.2	ps (rms)	1,2,4,6
	t_{jphQPI_SMI}	QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.14	0.2	ps (rms)	1,5,6
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.01	0.1	ps (rms)	1,5,6
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.01	0.1	ps (rms)	1,5,6

¹ Applies to all outputs.

² See <http://www.pcisig.com> for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ Subject to final radification by PCI SIG.

⁵ Calculated from Intel-supplied Clock Jitter Tool v 1.6.3

⁶ For RMS figures, additive jitter is calculated by solving the following equation: $(\text{Additive jitter})^2 = (\text{total jitter})^2 - (\text{input jitter})^2$

Clock Periods–Differential Outputs with Spread Spectrum Disabled

SSC OFF	Center Freq. MHz	Measurement Window							Units
		1 Clock	1 μ s	0.1s	0.1s	0.1s	1 μ s	1 Clock	
		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	
DIF	100.00	9.94900		9.99900	10.00000	10.00100		10.05100	ns
	133.33	7.44925		7.49925	7.50000	7.50075		7.55075	ns

Clock Periods–Differential Outputs with Spread Spectrum Enabled

SSC ON	Center Freq. MHz	Measurement Window							Units	Notes
		1 Clock	1 μ s	0.1s	0.1s	0.1s	1 μ s	1 Clock		
		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max		
DIF	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2,3
	133.00	7.44930	7.49930	7.51805	7.51880	7.51955	7.53830	7.58830	ns	1,2,4

Notes:

¹ Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK420BQ/CK410B+ accuracy requirements (+/-100ppm). The 9ZXL1231 itself does not contribute to ppm error.

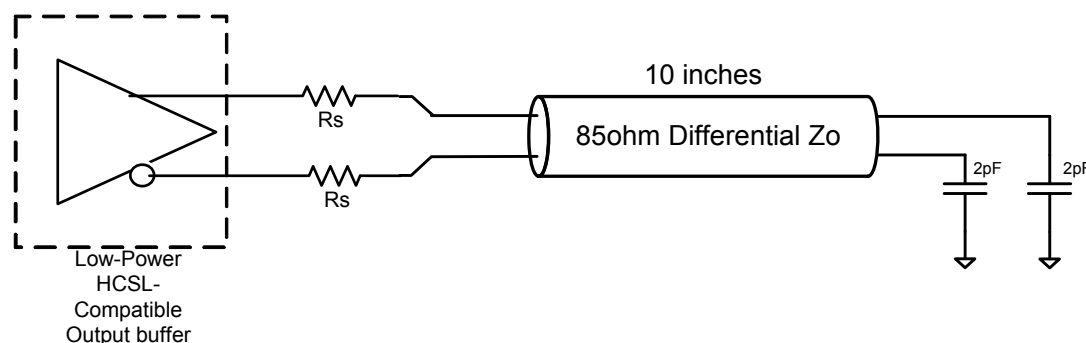
³ Driven by SRC output of main clock, 100 MHz PLL Mode or Bypass mode

⁴ Driven by CPU output of main clock, 133 MHz PLL Mode or Bypass mode

Differential Output Terminations

DIF Zo (Ω)	Rs (Ω)
100	33
85	27

9ZXL Differential Test Loads



General SMBus Serial Interface Information for 9ZXL1231

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRIte		
			ACK
Beginning Byte = N			
			ACK
Data Byte Count = X			
			ACK
Beginning Byte N			X Byte
		ACK	
O			
O		O	
O		O	
		O	
Byte N + X - 1			
			ACK
P	stoP bit		

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)		X Byte	IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
RT	Repeat starT		
Slave Address			
RD	ReaD		
			ACK
			Data Byte Count=X
ACK			
			Beginning Byte N
ACK			
			O
O			O
O			O
O			
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

SMBusTable: PLL Mode, and Frequency Select Register

Byte 0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	5	PLL Mode 1	PLL Operating Mode Rd back 1	R	See PLL Operating Mode Readback Table		Latch
Bit 6	5	PLL Mode 0	PLL Operating Mode Rd back 0	R			Latch
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3		PLL_SW_EN	Enable SW control of PLL BW	RW	HW Latch	SMBus Control	0
Bit 2		PLL Mode 1	PLL Operating Mode 1	RW	See PLL Operating Mode Readback Table		1
Bit 1		PLL Mode 0	PLL Operating Mode 1	RW			1
Bit 0	4	100M_133M#	Frequency Select Readback	R	133MHz	100MHz	Latch

Note: Setting bit 3 to '1' allows the user to override the Latch value from pin 5 via use of bits 2 and 1. Use the values from the PLL Operating Mode Readback Table. Note that Bits 7 and 6 will keep the value originally latched on pin 5. A warm reset of the system will have to be accomplished if the user changes these bits.

SMBusTable: Output Control Register

Byte 1	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	47/46	DIF_7_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1
Bit 6	43/42	DIF_6_En	Output Control - '0' overrides OE# pin	RW			1
Bit 5	39/38	DIF_5_En	Output Control - '0' overrides OE# pin	RW			1
Bit 4	35/34	DIF_4_En	Output Control - '0' overrides OE# pin	RW			1
Bit 3	30/31	DIF_3_En	Output Control - '0' overrides OE# pin	RW			1
Bit 2	26/27	DIF_2_En	Output Control - '0' overrides OE# pin	RW			1
Bit 1	21/22	DIF_1_En	Output Control - '0' overrides OE# pin	RW			1
Bit 0	17/18	DIF_0_En	Output Control - '0' overrides OE# pin	RW			1

SMBusTable: Output Control Register

Byte 2	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3	64/63	DIF_11_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1
Bit 2	59/60	DIF_10_En	Output Control - '0' overrides OE# pin	RW			1
Bit 1	54/55	DIF_9_En	Output Control - '0' overrides OE# pin	RW			1
Bit 0	50/51	DIF_8_En	Output Control - '0' overrides OE# pin	RW			1

SMBusTable: Reserved Register

Byte 3	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

SMBusTable: Reserved Register

Byte 4	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

SMBusTable: Vendor & Revision ID Register

Byte 5	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3	REVISION ID	R	A rev = 0000		X
Bit 6	-	RID2		R			X
Bit 5	-	RID1		R			X
Bit 4	-	RID0		R			X
Bit 3	-	VID3	VENDOR ID	R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1		R	-	-	0
Bit 0	-	VID0		R	-	-	1

SMBusTable: DEVICE ID

Byte 6	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-		Device ID 7 (MSB)	R	1231 is 231 Decimal or E7 Hex		1
Bit 6	-		Device ID 6	R			1
Bit 5	-		Device ID 5	R			1
Bit 4	-		Device ID 4	R			0
Bit 3	-		Device ID 3	R			0
Bit 2	-		Device ID 2	R			1
Bit 1	-		Device ID 1	R			1
Bit 0	-		Device ID 0	R			1

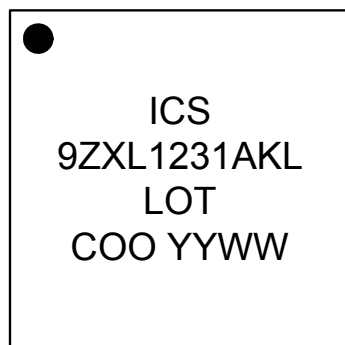
SMBusTable: Byte Count Register

Byte 7	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4	-	BC4	Writing to this register configures how many bytes will be read back.	RW	Default value is 8 hex, so 9 bytes (0 to 8) will be read back by default.		0
Bit 3	-	BC3		RW			1
Bit 2	-	BC2		RW			0
Bit 1	-	BC1		RW			0
Bit 0	-	BC0		RW			0

SMBusTable: Reserved Register

Byte 8	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

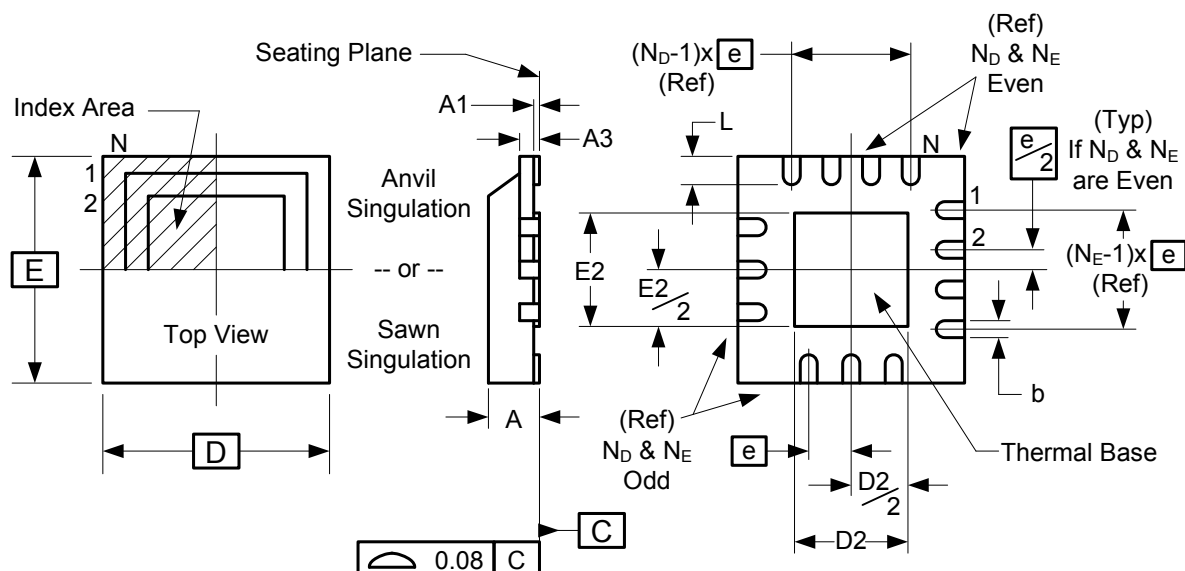
Marking Diagram



Notes:

1. “L” denotes RoHS compliant package.
2. ‘LOT’ denotes the lot number.
3. “COO”: country of origin.
4. YYWW is the last two digits of the year and week that the part was assembled.

Package Outline and Package Dimensions (64-pin MLF)



Symbol	Millimeters	
	Min	Max
A	0.8	1.0
A1	0	0.05
A3	0.25 Reference	
b	0.18	0.3
e	0.50 BASIC	
D x E BASIC	9.00 x 9.00	
D2 MIN./MAX.	6.00	6.25
E2 MIN./MAX.	6.00	6.25
L MIN./MAX.	0.30	0.50
N	64	
N _D	16	
N _E	16	

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
9ZXL1231AKLF	see page 15	Trays	64-pin MLF	0 to +70° C
9ZXL1231AKLFT		Tape and Reel	64-pin MLF	0 to +70° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

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Revision History

Rev.	Issuer	Issue Date	Description	Page #
A	RDW	4/14/2011	1. Updated Byte 0, PD# current and OE# Latency specs. 2. Updated electrical tables with Characterization Data. Move to Final 3. Corrected Pin Description, pin 37 was missing 4. Corrected Pin 5 in pinout. Name was truncated.	
B	RDW	8/3/2011	1. Functionality added to Byte 0 [3:1]. Byte 0, bit 3 enables SW control of PLL BW and Bypass mode. Byte 0[2:1] is read write to mimic the readback status of Byte 0[7:6]. See SMBus table.	
C	RDW	12/8/2011	1. Changed Output Features description 2. Fixed alignment issue in Power Connections Table - cosmetic fix, table information was and is correct. 3. Updated tDSPO_BYP to +/-250ps 4. Updated Differential Test Loads Figure to indicate impedance and trace length. 5. Removed SMBus Address info on page 12, SMBus address is selectable as indicated on page 3. 6. Add revised downward in Current Consumption Table	1,2,8,9,11,12
D	RDW	4/9/2012	1. Corrected Power Connections table, first column, last row. VDD for DIF clocks are pins 24, 40 and 57.	2
E	RDW	5/11/2012	1. Minor updates to some typical values in electrical tables, missing typical values added. 2. DS title changed from "12-Output Low Power Differential Buffer for PCIe Gen3 and QPI" to "12-Output Low Power Differential Buffer for PCIe Gen1/2/3 and QPI" to emphasize backwards compatibility. 3. Added comment to Vswing parameter on input clock to denote that the value is a single-ended value. 4. Max IDDIO changed from 106mA to 110mA.	Various

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